COMPLIANT

HALOGEN FREE



Vishay Semiconductors

Hyperfast Rectifier, 15 A FRED Pt®



PRIMARY CHARACTERISTICS								
I _{F(AV)}	15 A							
V_{R}	300 V							
V _F at I _F	0.85 V							
t _{rr} typ.	See Recovery table							
T _J max.	175 °C							
Package	2L TO-220AC							
Circuit configuration	Single							

FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

300 V series are the state of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diodes in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Repetitive peak reverse voltage	V_{RRM}		300	V					
Average rectified forward current	I _{F(AV)}	T _C = 142 °C	15	^					
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	140	А					
Operating junction and storage temperatures	T_J , T_{Stg}		-65 to +175	°C					

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	Ι _R = 100 μΑ	300	-	-				
Forward voltage	V _F	I _F = 15 A	-	1.05	1.25	V			
		I _F = 15 A, T _J = 125 °C	-	0.85	1.00				
Reverse leakage current	I _R	$V_R = V_R$ rated	-	0.05	40				
neverse leakage current		$T_J = 125 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	12	400	μΑ			
Junction capacitance	C _T	V _R = 300 V	-	45	-	pF			
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH			



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST COI	MIN.	TYP.	MAX.	UNITS			
Reverse recovery time	t _{rr}	$I_F = 1.0 A, dI_F/dt = 3$	-	-	40				
		T _J = 25 °C		-	32	-	ns		
		T _J = 125 °C	I _F = 15 A dI _F /dt = - 200 A/μs - V _B = 200 V	-	45	-			
Peak recovery current	I _{RRM}	T _J = 25 °C		-	2.4	-	Α		
		T _J = 125 °C		-	6.1	-			
Reverse recovery charge	Q _{rr}	T _J = 25 °C	*H - 200 *	-	38	-	nC		
		T _J = 125 °C		-	137	-	IIC		

THERMAL - MECHANICAL SPECIFICATIONS (T _J = 25 °C unless otherwise noted)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C				
Thermal resistance, junction to case	R _{thJC}		-	1.02	2.0					
Thermal resistance, junction to ambient R _{thJA}		Typical socket mount	-	-	70	°C/W				
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.2	-					
Weight			-	2.0	-	g				
vveignt			-	0.07	-	OZ.				
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)				
Marking device		Case style 2L TO-220AC	15ETH03							

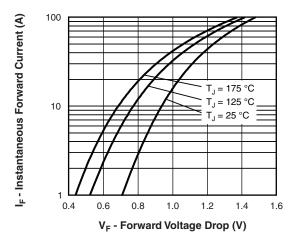


Fig. 1 - Typical Forward Voltage Drop Characteristics

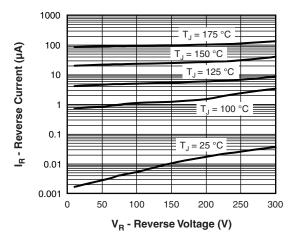


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

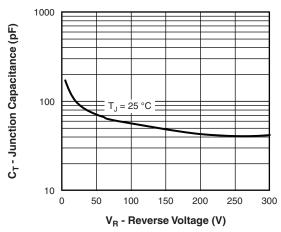


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

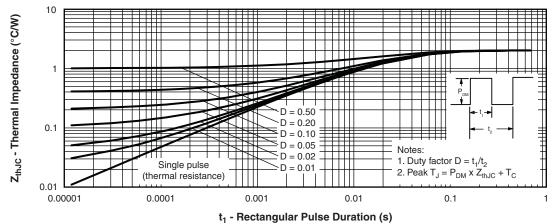


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

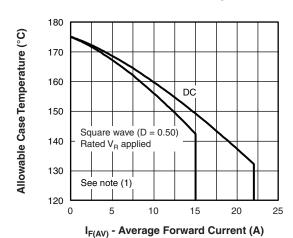
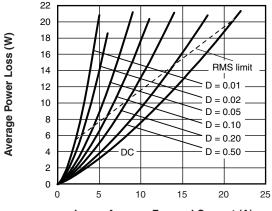


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current



 $I_{F(AV)}$ - Average Forward Current (A)

Fig. 6 - Forward Power Loss Characteristics

Note

 $\begin{array}{ll} \text{(1)} \ \ \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see Fig. 6)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$



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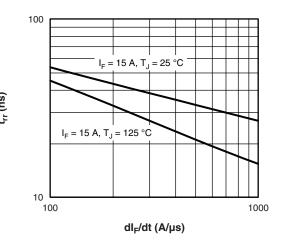


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

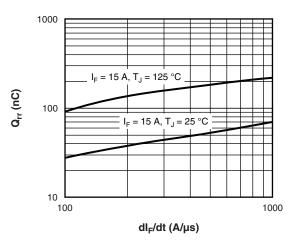
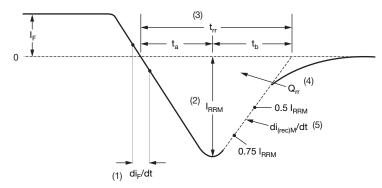


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

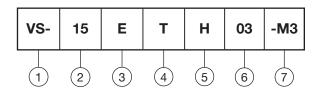
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

2 - Current rating (15 = 15 A)

3 - E = single diode

4 - Package:

T = 2L TO-220AC

5 - H = hyperfast recovery

6 - Voltage rating (03 = 300 V)

7 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

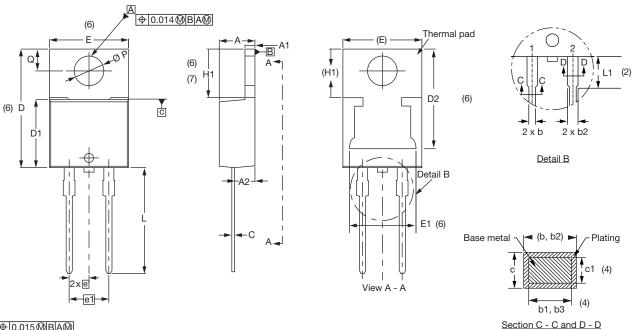
ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-15ETH03-M3	50	1000	Antistatic plastic tube						

LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?96156						
Part marking information	www.vishay.com/doc?95391						

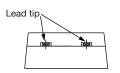


2L TO-220AC

DIMENSIONS in millimeters and inches







Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIMETERS		INC	HES	NOTES	NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183			D2	11.68	12.88	0.460	0.507	6
A1	1.14	1.40	0.045	0.055			Е	10.11	10.51	0.398	0.414	3, 6
A2	2.50	2.92	0.098	0.115			E1	6.86	8.89	0.270	0.350	6
b	0.69	1.01	0.027	0.040			е	2.41	2.67	0.095	0.105	
b1	0.38	0.97	0.015	0.038	4		e1	4.88	5.28	0.192	0.208	
b2	1.20	1.73	0.047	0.068			H1	6.09	6.48	0.240	0.255	6, 7
b3	1.14	1.73	0.045	0.068	4		L	13.52	14.02	0.532	0.552	
С	0.36	0.61	0.014	0.024			L1	3.32	3.82	0.131	0.150	2
c1	0.36	0.56	0.014	0.022	4		ØΡ	3.54	3.91	0.139	0.154	
D	14.85	15.35	0.585	0.604	3		Q	2.60	3.00	0.102	0.118	
D1	8.38	9.02	0.330	0.355				•	•			

Notes

- ⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2 (minimum)



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